

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A method of manufacturing a semiconductor device, the method comprising:
 - (a) sequentially stacking a semiconductor layer, a mask layer, and a metal layer on a substrate;
 - (b) anodizing the metal layer to transform the metal layer into a metal oxide layer including a plurality of nanoholes;
 - (c) etching the mask layer using the metal oxide layer as an etch mask until the nanoholes are extended to the surface of the semiconductor layer;
 - (d) removing the metal oxide layer by etching; and
 - (e) regrowing the semiconductor layer to completely fill nanoholes in the mask layer and extend above the mask layer and cover the mask layer between nanoholes,

wherein the semiconductor layer is formed of a nitride semiconductor.

2. (Original) The method of claim 1, wherein each of the holes has a diameter of about 10 nm to 500 nm.
3. (Original) The method of claim 1, wherein each of the holes occupies less than 50% of the entire area.

4. (Original) The method of claim 1, wherein the mask layer is formed to a thickness of about 50 nm to 500 nm.

5. (Previously Presented) The method of claim 1, wherein the semiconductor layer has a lattice constant which is different from the lattice constant of the substrate.

6. (Original) The method of claim 1, wherein the substrate is formed of one of an inorganic crystal including sapphire, Si, SiC, MgAl_2O_4 , NdGaO_3 , LiGaO_2 , ZnO, or MgO, a III-V group compound semiconductor including GaP or GaAs, and a III group nitride semiconductor including GaN.

7. (Cancelled)

8. (Currently Amended) The method of claim ~~[[7]]~~ 1, wherein the nitride semiconductor is one of GaN, InGaN, AlGaN, AlInGaN, and InGaNAs.

9. (Original) The method of claim 1, wherein the mask layer is formed of one of a polycrystalline semiconductor, a dielectric material, and a metal.

10. (Previously Presented) The method of claim 1, wherein the mask layer is formed of a polycrystalline semiconductor layer, which is one of polysilicon and polycrystalline nitride.

11. (Previously Presented) The method of claim 1, wherein the mask layer is one of silicon oxide, titanium oxide, and zirconium oxide.

12. (Previously Presented) The method of claim 1, wherein the mask layer is a metal that has a melting point of 1200 °C or higher.

13. (Previously Presented) The method of claim 12, wherein the metal of the mask layer is one of titanium and tungsten.

14. (Original) The method of claim 1, wherein the metal layer is formed of aluminum.

15. (Original) The method of claim 1, wherein in step (c), the etching process is a dry etch process.

16. (Cancelled)

17. (Cancelled)

18. (Previously Presented) The method of claim 1, wherein the semiconductor layer covers all of said mask layer.